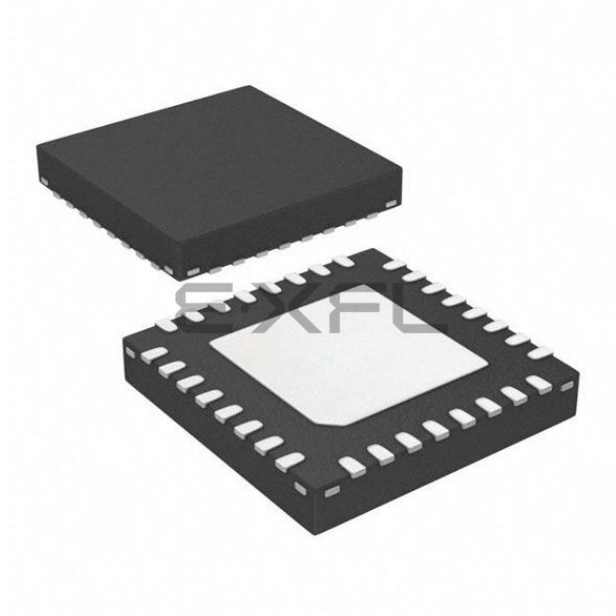

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I²C, Microwire, SPI, SSI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	28
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VQFN Exposed Pad
Supplier Device Package	32-HVQFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc11e11fhn33-101

6. Pinning information

6.1 Pinning

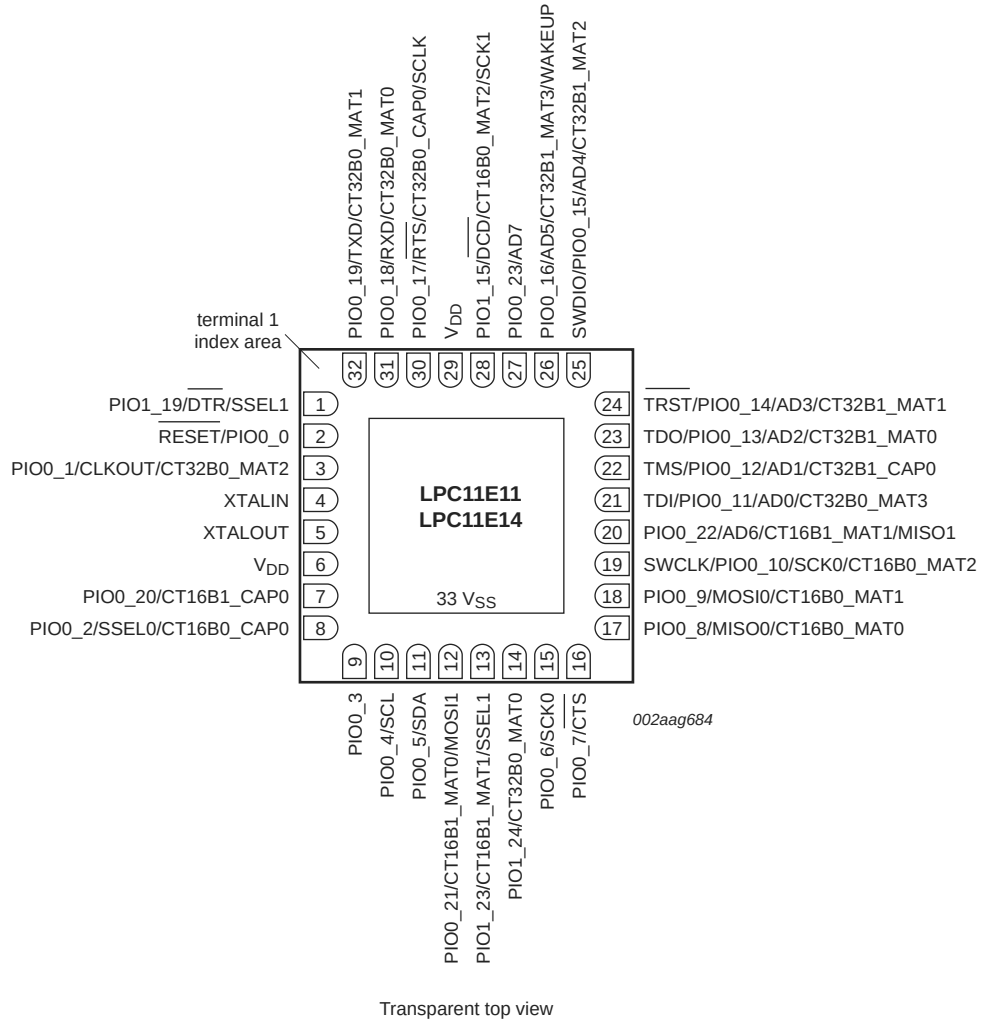


Fig 2. Pin configuration (HVQFN33)

Table 3. Pin description

Symbol	HVQFN33	LQFP48	LQFP64		Reset state [1]	Type	Description
PIO0_8/MISO0/ CT16B0_MAT0	17	27	36	[3]	I; PU	I/O	**PIO0_8 —** General purpose digital input/output pin.
					-	I/O	**MISO0 —** Master In Slave Out for SSP0.
					-	O	**CT16B0_MAT0 —** Match output 0 for 16-bit timer 0.
PIO0_9/MOSI0/ CT16B0_MAT1	18	28	37	[3]	I; PU	I/O	**PIO0_9 —** General purpose digital input/output pin.
					-	I/O	**MOSI0 —** Master Out Slave In for SSP0.
					-	O	**CT16B0_MAT1 —** Match output 1 for 16-bit timer 0.
SWCLK/PIO0_10/SCK0/ CT16B0_MAT2	19	29	38	[3]	I; PU	I	**SWCLK —** Serial wire clock and test clock TCK for JTAG interface.
					-	I/O	**PIO0_10 —** General purpose digital input/output pin.
					-	O	**SCK0 —** Serial clock for SSP0.
					-	O	**CT16B0_MAT2 —** Match output 2 for 16-bit timer 0.
TDI/PIO0_11/AD0/ CT32B0_MAT3	21	32	42	[6]	I; PU	I	**TDI —** Test Data In for JTAG interface.
					-	I/O	**PIO0_11 —** General purpose digital input/output pin.
					-	I	**AD0 —** A/D converter, input 0.
					-	O	**CT32B0_MAT3 —** Match output 3 for 32-bit timer 0.
TMS/PIO0_12/AD1/ CT32B1_CAP0	22	33	44	[6]	I; PU	I	**TMS —** Test Mode Select for JTAG interface.
					-	I/O	**PIO_12 —** General purpose digital input/output pin.
					-	I	**AD1 —** A/D converter, input 1.
					-	I	**CT32B1_CAP0 —** Capture input 0 for 32-bit timer 1.
TDO/PIO0_13/AD2/ CT32B1_MAT0	23	34	45	[6]	I; PU	O	**TDO —** Test Data Out for JTAG interface.
					-	I/O	**PIO0_13 —** General purpose digital input/output pin.
					-	I	**AD2 —** A/D converter, input 2.
					-	O	**CT32B1_MAT0 —** Match output 0 for 32-bit timer 1.
$\overline{\text{TRST}}$/PIO0_14/AD3/ CT32B1_MAT1	24	35	46	[6]	I; PU	I	**$\overline{\text{TRST}}$ —** Test Reset for JTAG interface.
					-	I/O	**PIO0_14 —** General purpose digital input/output pin.
					-	I	**AD3 —** A/D converter, input 3.
					-	O	**CT32B1_MAT1 —** Match output 1 for 32-bit timer 1.
SWDIO/PIO0_15/AD4/ CT32B1_MAT2	25	39	52	[6]	I; PU	I/O	**SWDIO —** Serial wire debug input/output.
					-	I/O	**PIO0_15 —** General purpose digital input/output pin.
					-	I	**AD4 —** A/D converter, input 4.
					-	O	**CT32B1_MAT2 —** Match output 2 for 32-bit timer 1.
PIO0_16/AD5/ CT32B1_MAT3/WAKEUP	26	40	53	[6]	I; PU	I/O	**PIO0_16 —** General purpose digital input/output pin.
					-	I	**AD5 —** A/D converter, input 5.
					-	O	**CT32B1_MAT3 —** Match output 3 for 32-bit timer 1.
					-	I	**WAKEUP —** Deep power-down mode wake-up pin with 20 ns glitch filter. Pull this pin HIGH externally to enter Deep power-down mode. Pull this pin LOW to exit Deep power-down mode. A LOW-going pulse as short as 50 ns wakes up the part.

[6] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors, configurable hysteresis, and analog input. When configured as a ADC input, digital section of the pad is disabled and the pin is not 5 V tolerant (see Figure 27); includes digital input glitch filter.

[7] When the system oscillator is not used, connect XTALIN and XTALOUT as follows: XTALIN can be left floating or can be grounded (grounding is preferred to reduce susceptibility to noise). Leave XTALOUT floating.

7.8.1 Features

- GPIO pins can be configured as input or output by software.
- All GPIO pins default to inputs with interrupt disabled at reset.
- Pin registers allow pins to be sensed and set individually.
- Up to eight GPIO pins can be selected from all GPIO pins to create an edge- or level-sensitive GPIO interrupt request.
- Any pin or pins in each port can trigger a port interrupt.

7.9 USART

The LPC11E1x contain one USART.

The USART includes full modem control, support for synchronous mode, and a smart card interface. The RS-485/9-bit mode allows both software address detection and automatic address detection using 9-bit mode.

The USART uses a fractional baud rate generator. Standard baud rates such as 115200 Bd can be achieved with any crystal frequency above 2 MHz.

7.9.1 Features

- Maximum USART data bit rate of 3.125 Mbit/s.
- 16 byte receive and transmit FIFOs.
- Register locations conform to 16C550 industry standard.
- Receiver FIFO trigger points at 1 B, 4 B, 8 B, and 14 B.
- Built-in fractional baud rate generator covering wide range of baud rates without a need for external crystals of particular values.
- Fractional divider for baud rate control, auto baud capabilities and FIFO control mechanism that enables software flow control implementation.
- Support for RS-485/9-bit mode.
- Support for modem control.
- Support for synchronous mode.
- Includes smart card interface.

7.10 SSP serial I/O controller

The SSP controllers operate on a SSP, 4-wire SSI, or Microwire bus. It can interact with multiple masters and slaves on the bus. Only a single master and a single slave can communicate on the bus during a given data transfer. The SSP supports full duplex transfers, with frames of 4 bit to 16 bit of data flowing from the master to the slave and from the slave to the master. In practice, often only one of these data flows carries meaningful data.

7.10.1 Features

- Maximum SSP speed of 25 Mbit/s (master) or 4.17 Mbit/s (slave) (in SSP mode)
- Compatible with Motorola SPI, 4-wire Texas Instruments SSI, and National Semiconductor Microwire buses

- Synchronous serial communication
- Master or slave operation
- 8-frame FIFOs for both transmit and receive
- 4-bit to 16-bit frame

7.11 I²C-bus serial I/O controller

The LPC11E1x contain one I²C-bus controller.

The I²C-bus is bidirectional for inter-IC control using only two wires: a Serial Clock line (SCL) and a Serial Data line (SDA). Each device is recognized by a unique address and can operate as either a receiver-only device (e.g., an LCD driver) or a transmitter with the capability to both receive and send information (such as memory). Transmitters and/or receivers can operate in either master or slave mode, depending on whether the chip has to initiate a data transfer or is only addressed. The I²C-bus is a multi-master bus, and more than one bus master connected to the interface can be controlled the bus.

7.11.1 Features

- The I²C-interface is an I²C-bus compliant interface with open-drain pins. The I²C-bus interface supports Fast-mode Plus with bit rates up to 1 Mbit/s.
- Easy to configure as master, slave, or master/slave.
- Programmable clocks allow versatile rate control.
- Bidirectional data transfer between masters and slaves.
- Multi-master bus (no central master).
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus.
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- The I²C-bus can be used for test and diagnostic purposes.
- The I²C-bus controller supports multiple address recognition and a bus monitor mode.

7.12 10-bit ADC

The LPC11E1x contains one ADC. It is a single 10-bit successive approximation ADC with eight channels.

7.12.1 Features

- 10-bit successive approximation ADC.
- Input multiplexing among 8 pins.
- Power-down mode.
- Measurement range 0 V to V_{DD}.
- 10-bit conversion time $\geq$ 2.44 μs (up to 400 kSamples/s).
- Burst conversion mode for single or multiple inputs.

- Optional conversion on transition of input pin or timer match signal.
- Individual result registers for each ADC channel to reduce interrupt overhead.

7.13 General purpose external event counter/timers

The LPC11E1x include two 32-bit counter/timers and two 16-bit counter/timers. The counter/timer is designed to count cycles of the system derived clock. It can optionally generate interrupts or perform other actions at specified timer values, based on four match registers. Each counter/timer also includes one capture input to trap the timer value when an input signal transitions, optionally generating an interrupt.

7.13.1 Features

- A 32-bit/16-bit timer/counter with a programmable 32-bit/16-bit prescaler.
- Counter or timer operation.
- Up to two capture channels per timer, that can take a snapshot of the timer value when an input signal transitions. A capture event can also generate an interrupt.
- Four match registers per timer that allow:
  - Continuous operation with optional interrupt generation on match.
  - Stop timer on match with optional interrupt generation.
  - Reset timer on match with optional interrupt generation.
- Up to four external outputs corresponding to match registers, with the following capabilities:
  - Set LOW on match.
  - Set HIGH on match.
  - Toggle on match.
  - Do nothing on match.
- The timer and prescaler can be configured to be cleared on a designated capture event. This feature permits easy pulse-width measurement by clearing the timer on the leading edge of an input pulse and capturing the timer value on the trailing edge.

7.14 System tick timer

The ARM Cortex-M0 includes a system tick timer (SYSTICK) that is intended to generate a dedicated SYSTICK exception at a fixed time interval (typically 10 ms).

7.15 Windowed WatchDog Timer (WWDT)

The purpose of the WWDT is to prevent an unresponsive system state. If software fails to update the watchdog within a programmable time window, the watchdog resets the microcontroller

7.15.1 Features

- Internally resets chip if not periodically reloaded during the programmable time-out period.
- Optional windowed operation requires reload to occur between a minimum and maximum time period, both programmable.

- Optional warning interrupt can be generated at a programmable time before watchdog time-out.
- Software enables the WWDT, but a hardware reset or a watchdog reset/interrupt is required to disable the WWDT.
- Incorrect feed sequence causes reset or interrupt, if enabled.
- Flag to indicate watchdog reset.
- Programmable 24-bit timer with internal prescaler.
- Selectable time period from ($T_{cy(WDCLK)} \times 256 \times 4$) to ($T_{cy(WDCLK)} \times 2^{24} \times 4$) in multiples of $T_{cy(WDCLK)} \times 4$.
- The Watchdog Clock (WDCLK) source can be selected from the IRC or the dedicated watchdog oscillator (WDO). The clock source selection provides a wide range of potential timing choices of watchdog operation under different power conditions.

7.16 Clocking and power control

7.16.1 Integrated oscillators

The LPC11E1x include three independent oscillators: the system oscillator, the Internal RC oscillator (IRC), and the watchdog oscillator. Each oscillator can be used for more than one purpose as required in a particular application.

Following reset, the LPC11E1x operates from the internal RC oscillator until software switches to a different clock source. The IRC allows the system to operate without any external crystal and the bootloader code to operate at a known frequency.

See Figure 6 for an overview of the LPC11E1x clock generation.

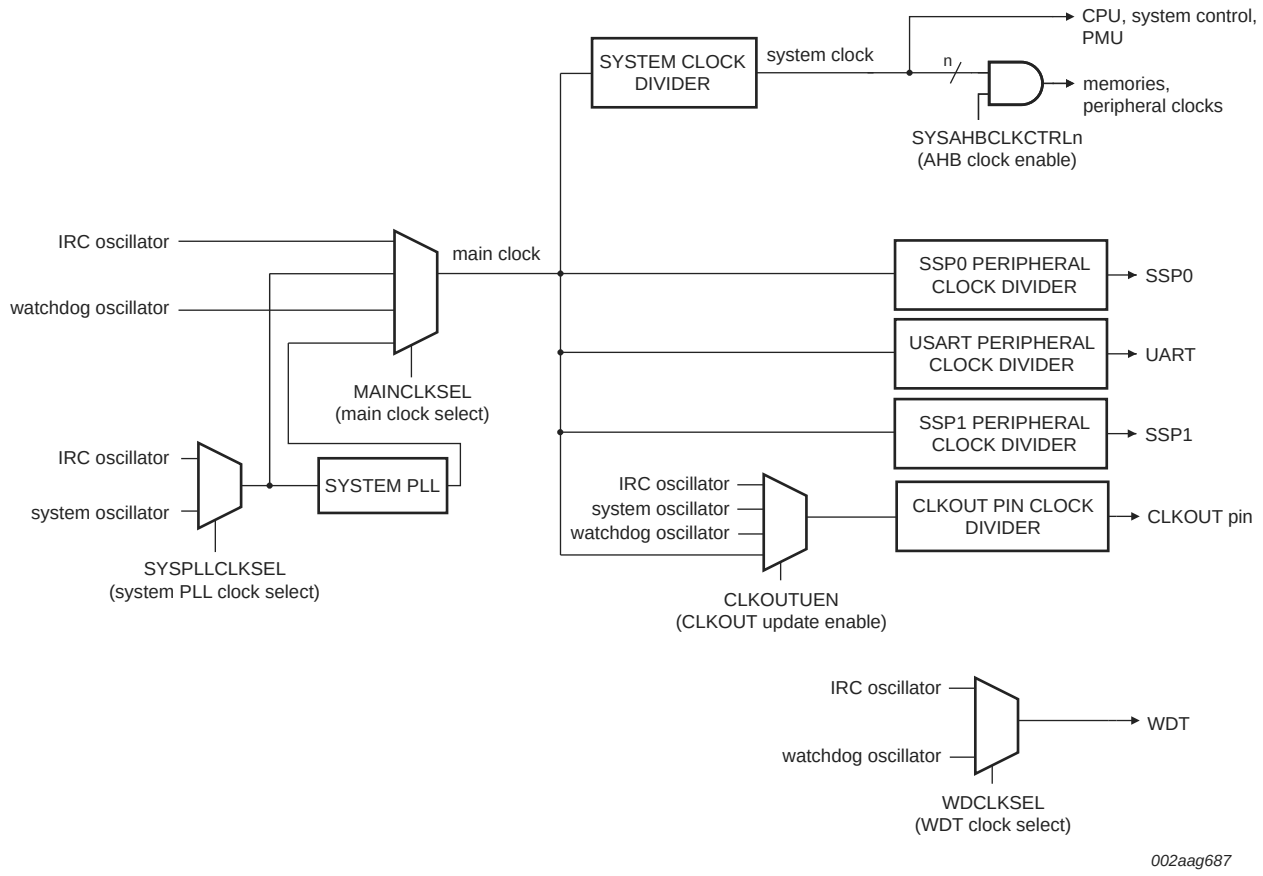


Fig 6. LPC11E1x clocking generation block diagram

7.16.1.1 Internal RC oscillator

The IRC can be used as the clock source for the WDT, and/or as the clock that drives the system PLL and then the CPU. The nominal IRC frequency is 12 MHz.

Upon power-up, any chip reset, or wake-up from Deep power-down mode, the LPC11E1x use the IRC as the clock source. Software can later switch to one of the other available clock sources.

7.16.1.2 System oscillator

The system oscillator can be used as the clock source for the CPU, with or without using the PLL.

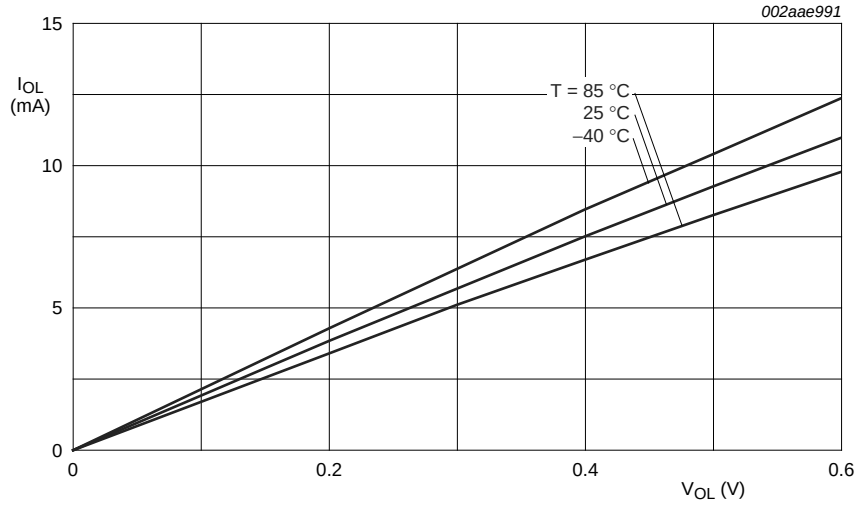
The system oscillator operates at frequencies of 1 MHz to 25 MHz. This frequency can be boosted to a higher frequency, up to the maximum CPU operating frequency, by the system PLL.

7.16.1.3 Watchdog oscillator

The watchdog oscillator can be used as a clock source that directly drives the CPU, the watchdog timer, or the CLKOUT pin. The watchdog oscillator nominal frequency is programmable between 7.8 kHz and 1.7 MHz. The frequency spread over processing and temperature is ±40 % (see also Table 13).

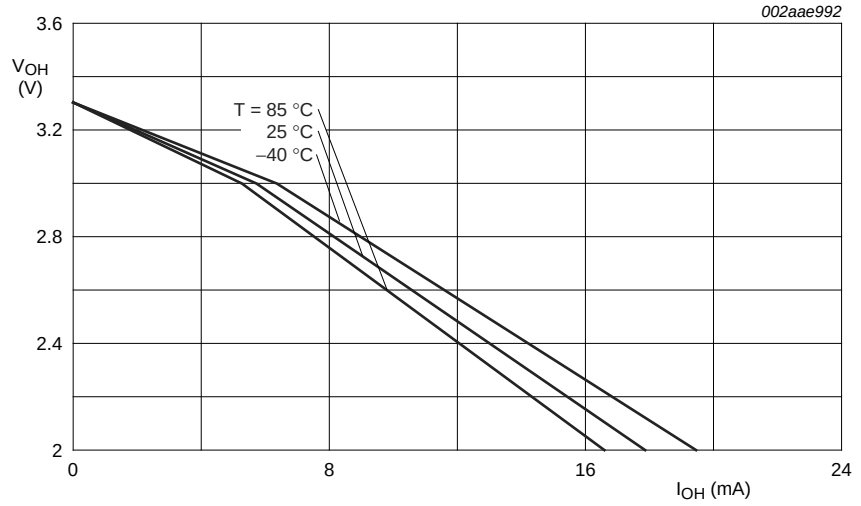
Table 8. Power consumption for individual analog and digital blocks

Peripheral	Typical supply current in mA			Notes
	n/a	12 MHz	48 MHz	
IRC	0.27	-	-	System oscillator running; PLL off; independent of main clock frequency.
System oscillator at 12 MHz	0.22	-	-	IRC running; PLL off; independent of main clock frequency.
Watchdog oscillator at 500 kHz/2	0.004	-	-	System oscillator running; PLL off; independent of main clock frequency.
BOD	0.051	-	-	Independent of main clock frequency.
Main PLL	-	0.21	-	-
ADC	-	0.08	0.29	-
CLKOUT	-	0.12	0.47	Main clock divided by 4 in the CLKOUTDIV register.
CT16B0	-	0.02	0.06	-
CT16B1	-	0.02	0.06	-
CT32B0	-	0.02	0.07	-
CT32B1	-	0.02	0.06	-
GPIO	-	0.23	0.88	GPIO pins configured as outputs and set to LOW. Direction and pin state are maintained if the GPIO is disabled in the SYSAHBCLKCFG register.
IOCONFIG	-	0.03	0.10	-
I2C	-	0.04	0.13	-
ROM	-	0.04	0.15	-
SPI0	-	0.12	0.45	-
SPI1	-	0.12	0.45	-
UART	-	0.22	0.82	-
WWDT	-	0.02	0.06	Main clock selected as clock source for the WDT.



Conditions: V_{DD} = 3.3 V; standard port pins and PIO0_7.

Fig 16. Typical LOW-level output current I_{OL} versus LOW-level output voltage V_{OL}



Conditions: V_{DD} = 3.3 V; standard port pins.

Fig 17. Typical HIGH-level output voltage V_{OH} versus HIGH-level output source current I_{OH}

[2] The typical frequency spread over processing and temperature (T_{amb} = −40 °C to +85 °C) is ±40 %.

[3] See the *LPC11Exx user manual.*

10.4 I/O pins

Table 14. Dynamic characteristics: I/O pins[1]
T_{amb} = −40 °C to +85 °C; 3.0 V ≤ V_{DD} ≤ 3.6 V.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_r	rise time	pin configured as output	3.0	-	5.0	ns
t_f	fall time	pin configured as output	2.5	-	5.0	ns

[1] Applies to standard port pins and $\overline{\text{RESET}}$ pin.

10.5 I²C-bus

Table 15. Dynamic characteristic: I²C-bus pins[1]
T_{amb} = −40 °C to +85 °C.[2]

Symbol	Parameter		Conditions	Min	Max	Unit
f_{SCL}	SCL clock frequency		Standard-mode	0	100	kHz
			Fast-mode	0	400	kHz
			Fast-mode Plus	0	1	MHz
t_f	fall time	[4][5][6][7]	of both SDA and SCL signals	-	300	ns
			Standard-mode			
			Fast-mode	20 + 0.1 × C_b	300	ns
			Fast-mode Plus	-	120	ns
t_{LOW}	LOW period of the SCL clock		Standard-mode	4.7	-	µs
			Fast-mode	1.3	-	µs
			Fast-mode Plus	0.5	-	µs
t_{HIGH}	HIGH period of the SCL clock		Standard-mode	4.0	-	µs
			Fast-mode	0.6	-	µs
			Fast-mode Plus	0.26	-	µs
$t_{HD;DAT}$	data hold time	[3][4][8]	Standard-mode	0	-	µs
			Fast-mode	0	-	µs
			Fast-mode Plus	0	-	µs
$t_{SU;DAT}$	data set-up time	[9][10]	Standard-mode	250	-	ns
			Fast-mode	100	-	ns
			Fast-mode Plus	50	-	ns

[1] See the I²C-bus specification *UM10204* for details.

[2] Parameters are valid over operating temperature range unless otherwise specified.

[3] tHD;DAT is the data hold time that is measured from the falling edge of SCL; applies to data in transmission and the acknowledge.

[4] A device must internally provide a hold time of at least 300 ns for the SDA signal (with respect to the V_{IH}(min) of the SCL signal) to bridge the undefined region of the falling edge of SCL.

[5] C_b = total capacitance of one bus line in pF.

[6] The maximum t_f for the SDA and SCL bus lines is specified at 300 ns. The maximum fall time for the SDA output stage t_f is specified at 250 ns. This allows series protection resistors to be connected in between the SDA and the SCL pins and the SDA/SCL bus lines without exceeding the maximum specified t_f.

[7] In Fast-mode Plus, fall time is specified the same for both output stage and bus timing. If series resistors are used, designers should allow for this when considering bus timing.

[8] The maximum $t_{HD;DAT}$ could be 3.45 μs and 0.9 μs for Standard-mode and Fast-mode but must be less than the maximum of $t_{VD;DAT}$ or $t_{VD;ACK}$ by a transition time (see *UM10204*). This maximum must only be met if the device does not stretch the LOW period (t_{LOW}) of the SCL signal. If the clock stretches the SCL, the data must be valid by the set-up time before it releases the clock.

[9] tSU;DAT is the data set-up time that is measured with respect to the rising edge of SCL; applies to data in transmission and the acknowledge.

[10] A Fast-mode I^2C-bus device can be used in a Standard-mode I^2C-bus system but the requirement $t_{SU;DAT}$ = 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line $t_{r(max)} + t_{SU;DAT}$ = 1000 + 250 = 1250 ns (according to the Standard-mode I^2C-bus specification) before the SCL line is released. Also the acknowledge timing must meet this set-up time.

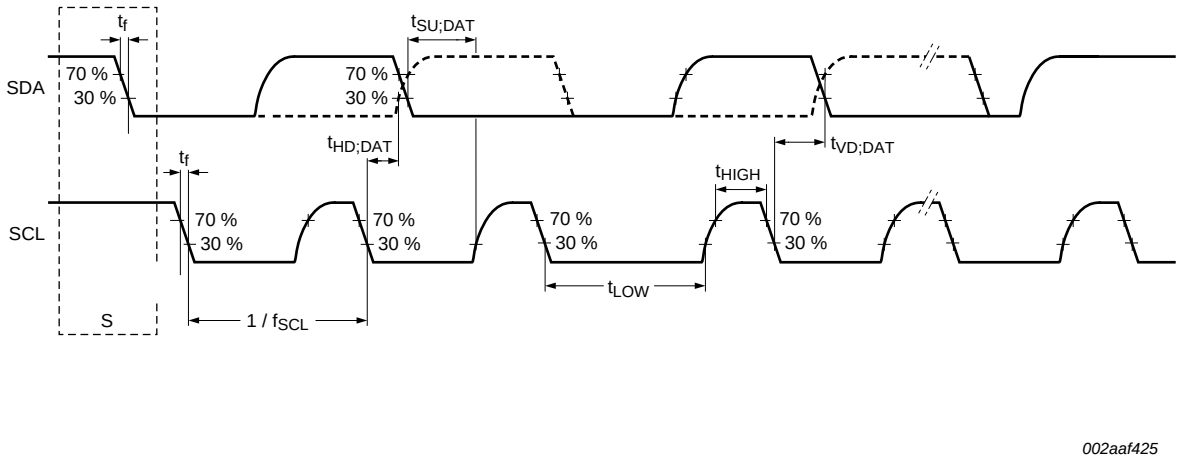


Fig 22. I^2C-bus pins clock timing

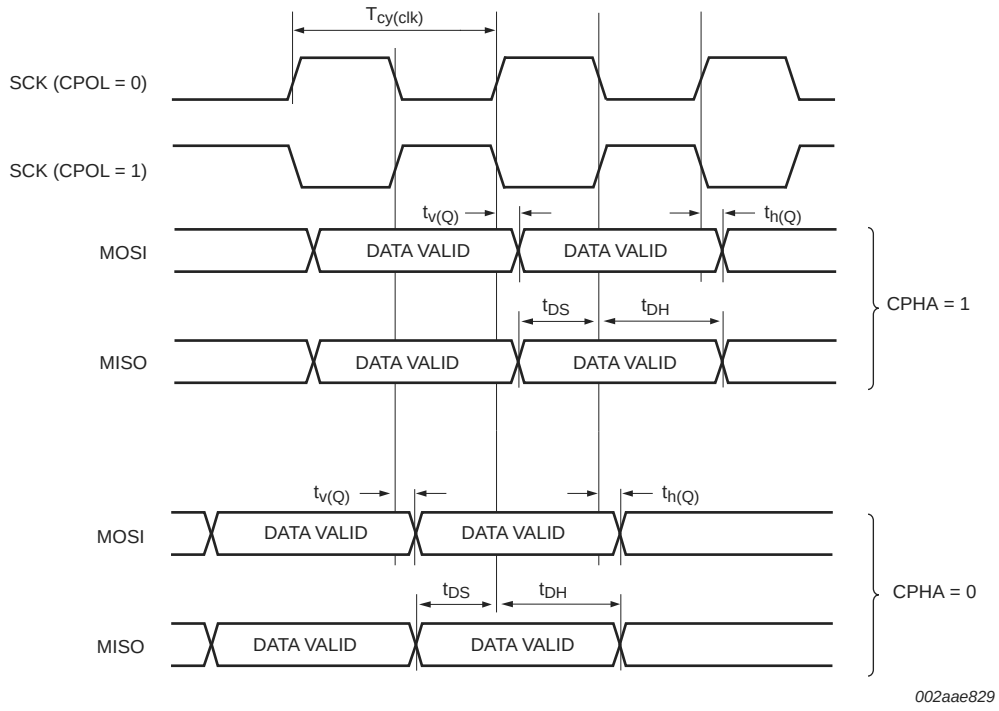


Fig 23. SSP master timing in SPI mode

11. Application information

11.1 XTAL input

The input voltage to the on-chip oscillators is limited to 1.8 V. If the oscillator is driven by a clock in slave mode, it is recommended that the input be coupled through a capacitor with C_i = 100 pF. To limit the input voltage to the specified range, choose an additional capacitor to ground C_g which attenuates the input voltage by a factor $C_i/(C_i + C_g)$. In slave mode, a minimum of 200 mV(RMS) is needed.

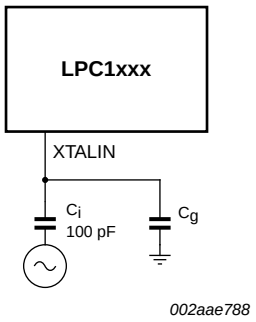


Fig 25. Slave mode operation of the on-chip oscillator

In slave mode, couple the input clock signal with a capacitor of 100 pF (Figure 25), with an amplitude between 200 mV(RMS) and 1000 mV(RMS). This signal corresponds to a square wave signal with a signal swing of between 280 mV and 1.4 V. The XTALOUT pin in this configuration can be left unconnected.

External components and models used in oscillation mode are shown in Figure 26 and in Table 17 and Table 18. Since the feedback resistance is integrated on chip, only a crystal and the capacitances C_{X1} and C_{X2} need to be connected externally in case of fundamental mode oscillation (L, C_L and R_S represent the fundamental frequency). Capacitance C_P in Figure 26 represents the parallel package capacitance and must not be larger than 7 pF. Parameters F_{OSC}, C_L, R_S and C_P are supplied by the crystal manufacturer.

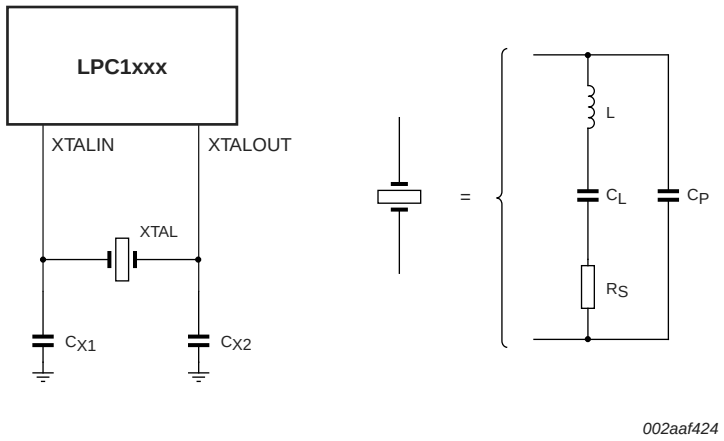


Fig 26. Oscillator modes and models: oscillation mode of operation and external crystal model used for C_{X1}/C_{X2} evaluation

Table 17. Recommended values for C_{X1}/C_{X2} in oscillation mode (crystal and external components parameters) low frequency mode

Fundamental oscillation frequency F_{OSC}	Crystal load capacitance C_L	Maximum crystal series resistance R_S	External load capacitors C_{X1}, C_{X2}
1 MHz to 5 MHz	10 pF	< 300 Ω	18 pF, 18 pF
	20 pF	< 300 Ω	39 pF, 39 pF
	30 pF	< 300 Ω	57 pF, 57 pF
5 MHz to 10 MHz	10 pF	< 300 Ω	18 pF, 18 pF
	20 pF	< 200 Ω	39 pF, 39 pF
	30 pF	< 100 Ω	57 pF, 57 pF
10 MHz to 15 MHz	10 pF	< 160 Ω	18 pF, 18 pF
	20 pF	< 60 Ω	39 pF, 39 pF
15 MHz to 20 MHz	10 pF	< 80 Ω	18 pF, 18 pF

Table 18. Recommended values for C_{X1}/C_{X2} in oscillation mode (crystal and external components parameters) high frequency mode

Fundamental oscillation frequency F_{OSC}	Crystal load capacitance C_L	Maximum crystal series resistance R_S	External load capacitors C_{X1}, C_{X2}
15 MHz to 20 MHz	10 pF	< 180 Ω	18 pF, 18 pF
	20 pF	< 100 Ω	39 pF, 39 pF
20 MHz to 25 MHz	10 pF	< 160 Ω	18 pF, 18 pF
	20 pF	< 80 Ω	39 pF, 39 pF

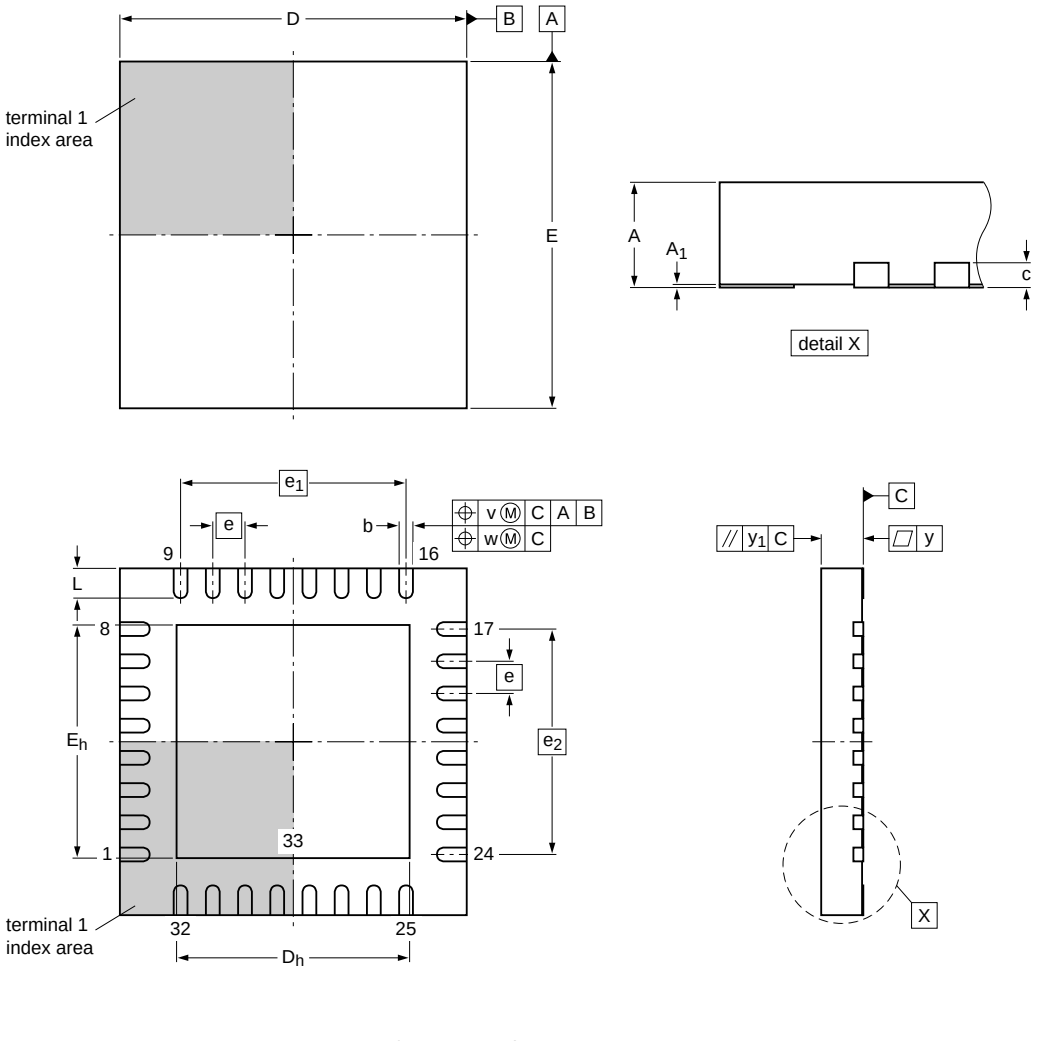
11.2 XTAL Printed-Circuit Board (PCB) layout guidelines

Follow these guidelines for PCB layout:

- Connect the crystal on the PCB as close as possible to the oscillator input and output pins of the chip.
- Take care that the load capacitors C_{x1}, C_{x2}, and C_{x3} in case of third overtone crystal use have a common ground plane.

12. Package outline

HVQFN33: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 x 7 x 0.85 mm



Dimensions

Unit		$A^{(1)}$	A_1	b	c	$D^{(1)}$	D_h	$E^{(1)}$	E_h	e	e_1	e_2	L	v	w	y	y_1
	max	1.00	0.05	0.35		7.1	4.85	7.1	4.85				0.75				
mm	nom	0.85	0.02	0.28	0.2	7.0	4.70	7.0	4.70	0.65	4.55	4.55	0.60	0.1	0.05	0.08	0.1
	min	0.80	0.00	0.23		6.9	4.55	6.9	4.55				0.45				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

hvqfn33_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
		- - -				~~09-03-17~~ 09-03-23

Fig 30. Package outline HVQFN33 (7 x 7 x 0.85 mm)

13. Soldering

Footprint information for reflow soldering of HVQFN33 package

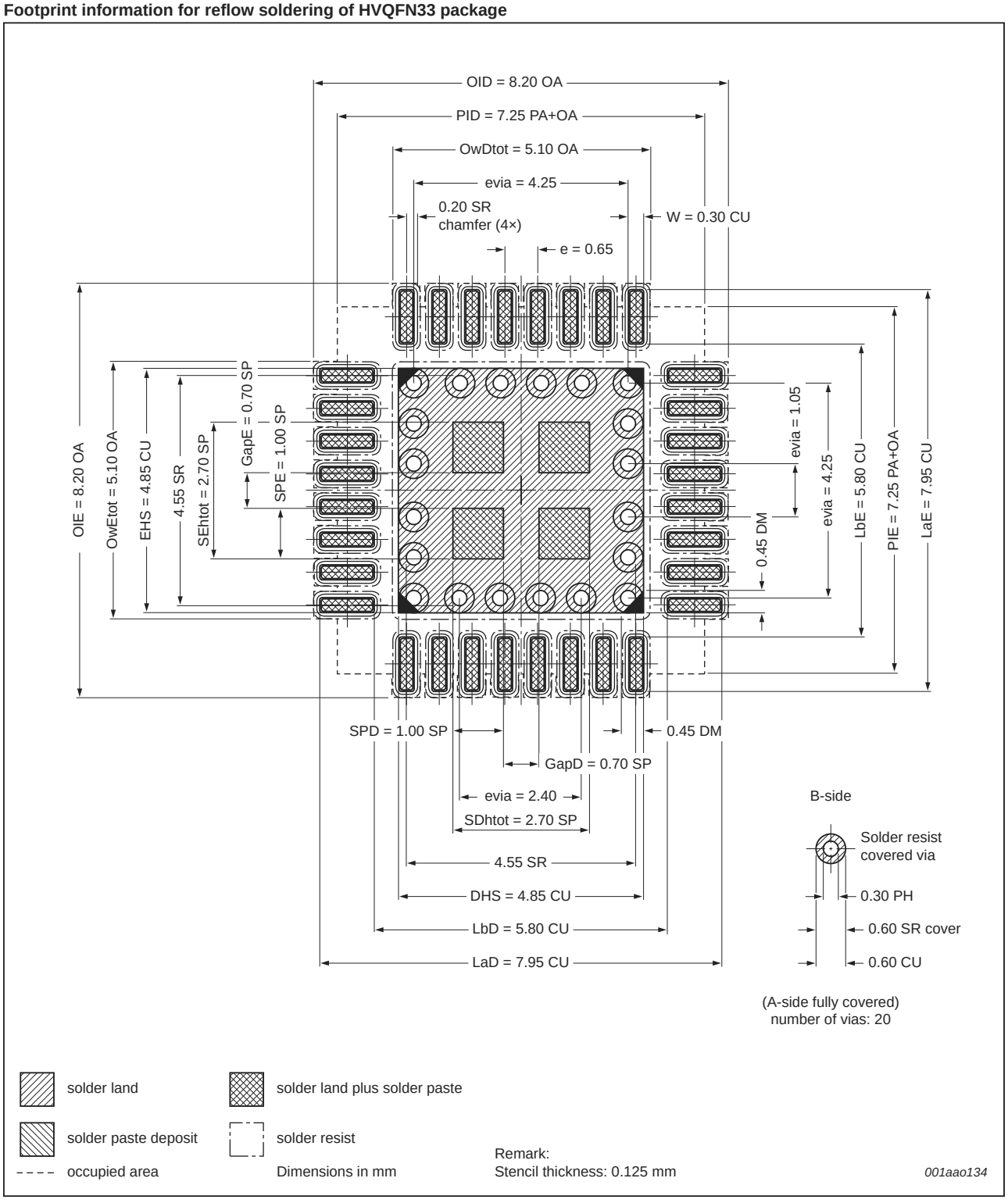
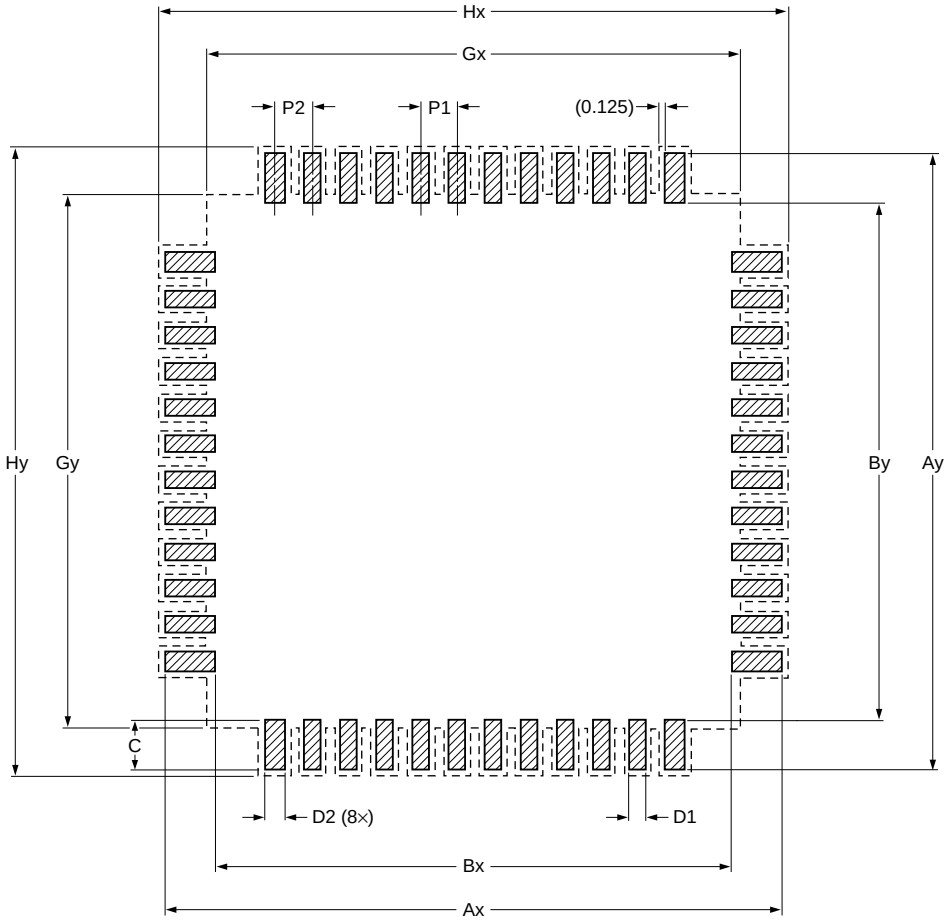


Fig 33. Reflow soldering for the HVQFN33 (7x7) package

Footprint information for reflow soldering of LQFP48 package **SOT313-2**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

occupied area

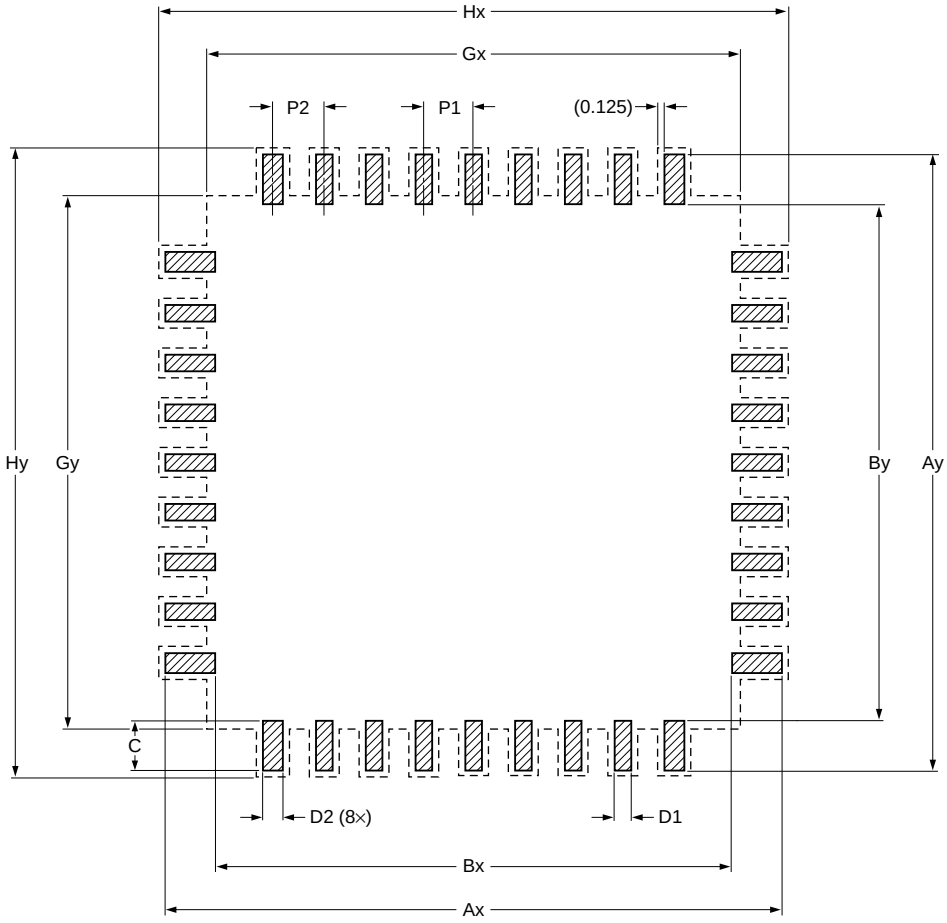
DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.560	10.350	10.350	7.350	7.350	1.500	0.280	0.500	7.500	7.500	10.650	10.650

sot313-2_fr

Fig 34. Reflow soldering for the LQFP48 package

Footprint information for reflow soldering of LQFP64 package **SOT314-2**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.560	13.300	13.300	10.300	10.300	1.500	0.280	0.400	10.500	10.500	13.550	13.550

sot314-2_fr

Fig 35. Reflow soldering for the LQFP64 package

15. Revision history

Table 20. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
LPC11E1X v.1.1	20130924	Product data sheet	-	LPC11E1X v.1
Modifications:	• Parameters t_{er} and f_{clk} removed in Table 10. • Table 3: Added “5 V tolerant pad” to $\overline{\text{RESET}}$/PIO0_0 table note. • Table 7: Removed BOD interrupt level 0. • Added Section 11.5 “ADC effective input impedance”. • Programmable glitch filter is enabled by default. See Section 7.7.1. • Table 5 “Static characteristics” added Pin capacitance section. • Table 4 “Limiting values”: – Updated V_{DD} min and max. – Updated V_I conditions. • Table 10 “EEPROM characteristics”: Changed the t_{prog} from 1.1 ms to 2.9 ms; the EEPROM IAP always does an erase and program, thus the total program time is $t_{er} + t_{prog}$.			
LPC11E1X v.1	20120220	Product data sheet	-	-